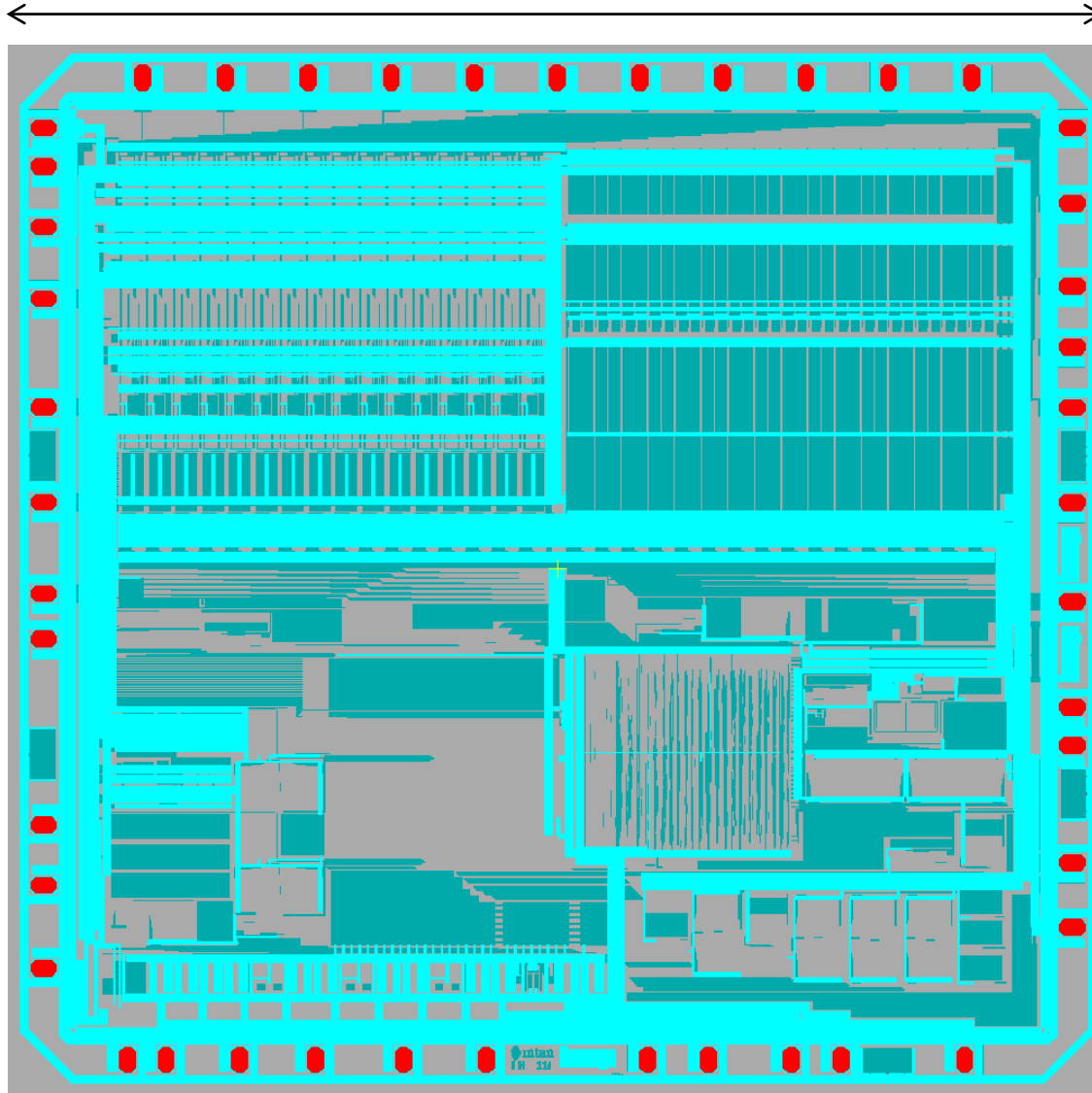


# Intan Technologies RHS2116 Bare Die

Approximately 4.9 mm



**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

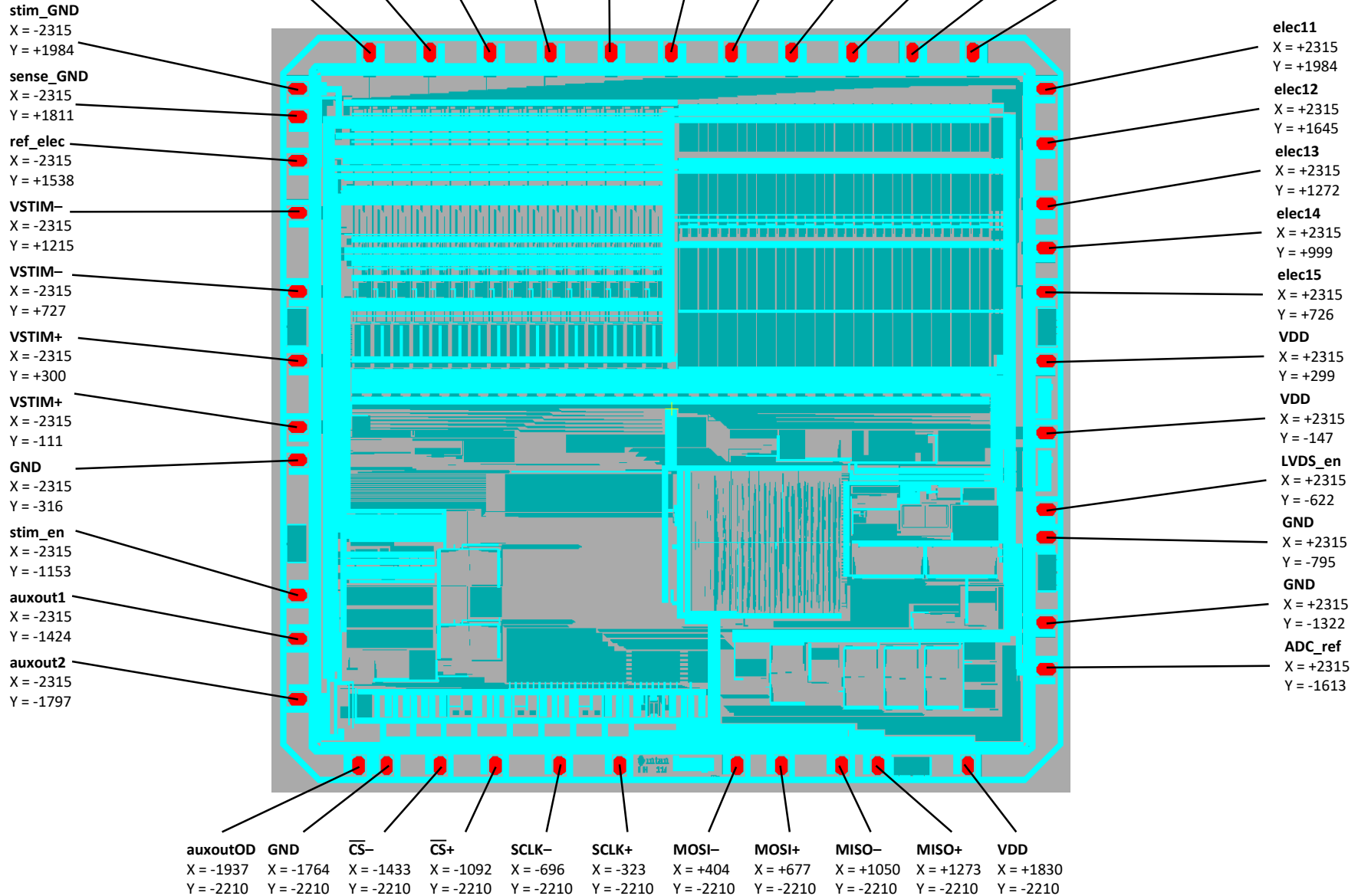
**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads

Approximately 4.7 mm

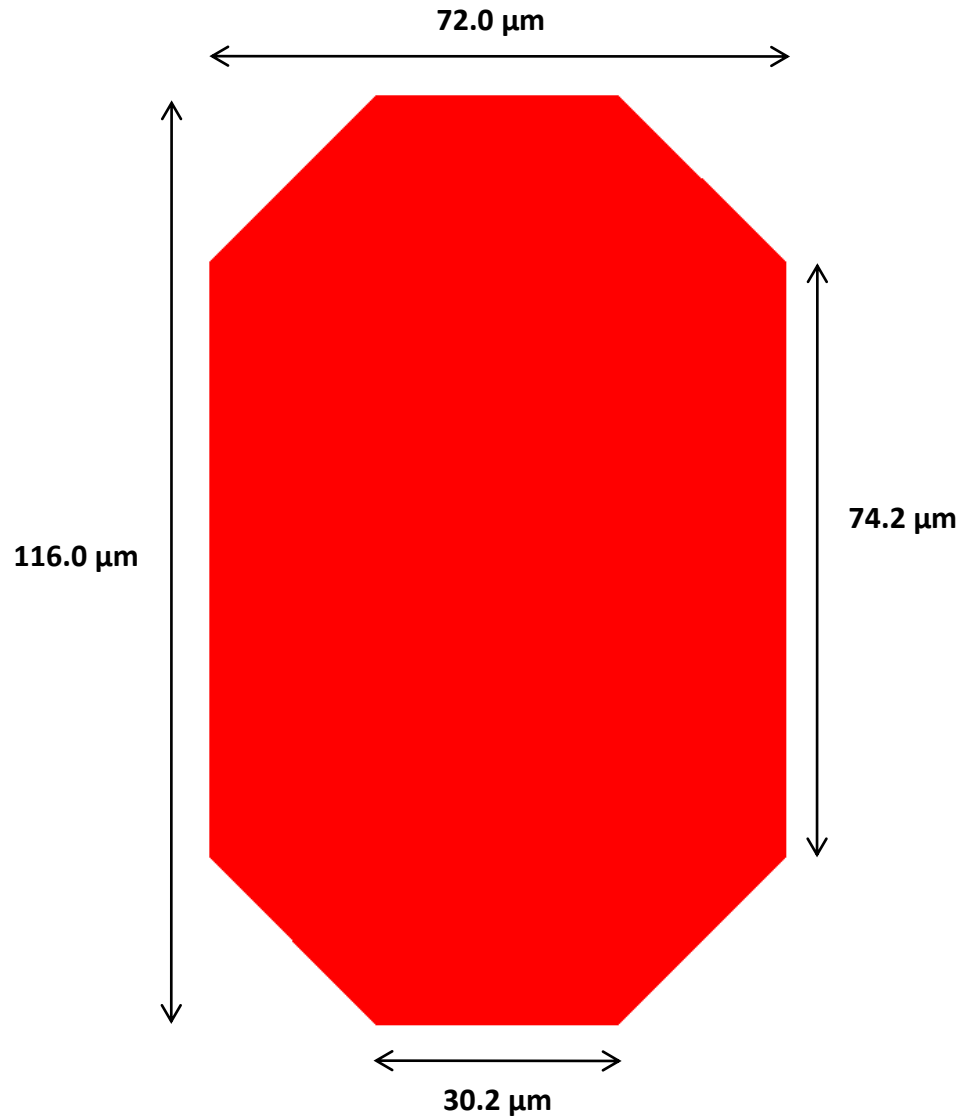
Each die is 0.20 mm (8 mils) thick

elec0	elec1	elec2	elec3	elec4	elec5	elec6	elec7	elec8	elec9	elec10
X = -1869	X = -1496	X = -1123	X = -750	X = -377	X = -4	X = +369	X = +742	X = +1115	X = +1488	X = +1861
Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210	Y = +2210



# Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper)



Minimum bond pad pitch (center to center):  $173\ \mu\text{m}$